SN54AHC16373, SN74AHC16373 16-BIT TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

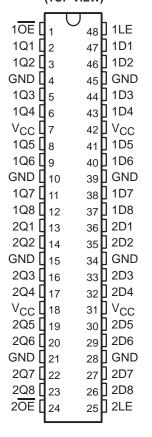
SCLS329G - MARCH 1996 - REVISED JANUARY 2000

- Members of the Texas Instruments
 Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V_{CC}
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'AHC16373 devices are 16-bit transparent D-type latches with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

SN54AHC16373 . . . WD PACKAGE SN74AHC16373 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels at the D inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54AHC16373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHC16373 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

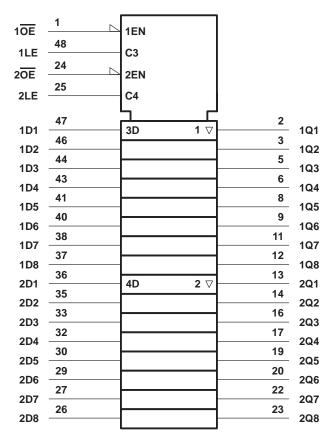
EPIC and Widebus are trademarks of Texas Instruments Incorporated.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

FUNCTION TABLE (each 8-bit latch)

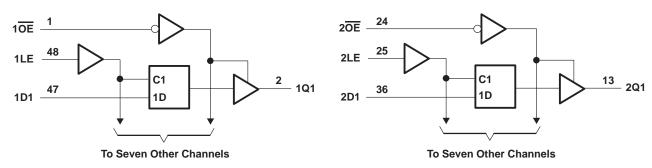
	INPUTS		ОИТРИТ
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	Χ	Χ	Z

logic symbol†



 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCLS329G - MARCH 1996 - REVISED JANUARY 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, $I_{ K }(V_{ C } < 0)$	–20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through each V _{CC} or GND	±75 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

			SN54AH	C16373	SN74AH0	C16373	UNIT
			MIN	MAX	MIN	MAX	UNII
Vсс	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
VIН	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		
		V _{CC} = 2 V		0.5		0.5	
VIL	Low-level input voltage	V _{CC} = 3 V		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65	
٧ı	Input voltage	-	0	5.5	0	5.5	V
٧o	Output voltage		0,4	Vcc	0	Vcc	V
		V _{CC} = 2 V	Ú	-50		- 50	μΑ
ЮН	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2	-4		-4	mA
		$V_{CC} = 5 V \pm 0.5 V$	Q.	-8		-8	mA
		V _{CC} = 2 V		50		50	μΑ
lOL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4		4	A
		$V_{CC} = 5 V \pm 0.5 V$		8		8	mA
44/454	lanut transition vice or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100		100	20/1
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		20		20	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN54AHC16373, SN74AHC16373 16-BIT TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCLS329G - MARCH 1996 - REVISED JANUARY 2000

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Voc	T,	ղ = 25°C	;	SN54AH0	C16373	SN74AHC	16373	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	1.9			1.9		1.9		
	I _{OH} = -50 μA	3 V	2.9			2.9		2.9		
Voн		4.5 V	4.4			4.4		4.4		V
	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8	N.	3.8		
		2 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1	Ġ	0.1		0.1	
VOL		4.5 V			0.1	40	0.1		0.1	V
	I _{OL} = 4 mA	3 V			0.36	20	0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36	² O	0.5		0.44	
lլ	$V_I = V_{CC}$ or GND	0 V to 5.5 V			±0.1	y	±1*		±1	μΑ
loz	$V_O = V_{CC}$ or GND, $V_I = V_{IL}$ or V_{IH}	5.5 V			±0.25		±2.5		±2.5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40	μΑ
Ci	V _I = V _{CC} or GND	5 V		2.5	10				10	pF
Co	$V_O = V_{CC}$ or GND	5 V		4						pF

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 \text{ V}$.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = :	25°C	SN54AH	C16373	SN74AHC	16373	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high	5		5	2011	5		ns
t _{su}	Setup time, data before LE↓	4		4		4		ns
t _h	Hold time, data after LE↓	1		र १		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		$T_A = 2$	25°C	SN54AH	C16373	SN74AHC	16373	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNII
t _W	Pulse duration, LE high	5		5	100	5		ns
t _{su}	Setup time, data before LE↓	4		4		4		ns
t _h	Hold time, data after LE↓	1		र्भ		1		ns

SCLS329G - MARCH 1996 - REVISED JANUARY 2000

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	չ = 25°C	;	SN54AHC	16373	SN74AHC	16373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	D	Q	C _I = 15 pF		7.3*	13*	1*	15*	1	15	ns
t _{PHL}	D	Q	C[= 15 pi		7.3*	13*	1*	15*	1	15	115
t _{PLH}	LE	Q	C _L = 15 pF		7*	13*	1*	15*	1	15	ns
tPHL	LE	Q	CL = 15 pr		7*	13*	1**	15*	1	15	110
t _{PZH}	ŌĒ	Q	C 15 pE		7.3*	13*	1*	15*	1	15	ns
tPZL	OE	Q	C _L = 15 pF		7.3*	13*	1*	15*	1	15	115
t _{PHZ}	ŌĒ	Q	C _I = 15 pF		10*	14*	1*	16*	1	16	ns
t _{PLZ}	OE	Q	C[= 15 pr		10*	14*	1* 4	16*	1	16	1115
t _{PLH}	D	Q	C _I = 50 pF		9.8	14	10	16	1	16	ns
tPHL	D	Q	CL = 50 pr		9.8	14	70	16	1	16	110
tPLH	LE	Q	C 50 pF		9.5	14.5	æ 1	16.5	1	16.5	ns
tPHL	LE	α	C _L = 50 pF		9.5	14.5	1	16.5	1	16.5	110
^t PZH		0	C. 50 pF		9.3	14.9	1	16	1	16	
tPZL	ŌĒ	Q	C _L = 50 pF		8	14.9	1	16	1	16	ns
t _{PHZ}	0.5	Q	C. = 50 pE		10.4	15.5	1	17	1	17	ns
t _{PLZ}	ŌĒ	Q	$C_L = 50 \text{ pF}$		11.6	15.5	1	17	1	17	115
tsk(o)		·	C _L = 50 pF			1.5**		·		1.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	չ = 25°C	;	SN54AHC	16373	SN74AHC	16373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
tPLH	D	Q	C _I = 15 pF		5*	8.2*	1*	9.5*	1	9.5	ns
tPHL	D	Q	CL = 15 pr		5*	8.2*	1*	9.5*	1	9.5	115
tPLH	LE	Q	C: -15 pE		4.9*	8.5*	1*	9.5*	1	9.5	ns
tPHL	LE	Q	C _L = 15 pF		4.9*	8.5*	1*	9.5*	1	9.5	115
t _{PZH}	ŌĒ	Q	C 15 pF		5.5*	9.1*	1*	10*	1	10	no
tPZL	OE	Q	C _L = 15 pF		5.5*	9.1*	1*	10*	1	10	ns
t _{PHZ}	ŌĒ	0	C. 15 pF		5*	9.5*	1*	10*	1	10	
tPLZ	OE	Q	C _L = 15 pF		5*	9.5*	1* <	10*	1	10	ns
t _{PLH}	D	Q	C. 50 pF		6.5	9.2	10	10.5	1	10.5	
tPHL	D	Q	C _L = 50 pF		6.5	9.2	d	10.5	1	10.5	ns
t _{PLH}	LE	Q	C 50 pF		6.4	9.5	<u>ر</u> 1	10.5	1	10.5	ns
t _{PHL}	LE	Q	$C_L = 50 \text{ pF}$		6.4	9.5	1	10.5	1	10.5	115
t _{PZH}	ŌĒ	Q	C: - 50 pF		6	10.1	1	11.5	1	11.5	ns
tPZL	OE	Q	C _L = 50 pF		6	10.1	1	11.5	1	11.5	115
tPHZ	ŌĒ	Q	C _I = 50 pF		6.5	10.5	1	11.5	1	11.5	ns
tPLZ	OE	α	CL = 50 pr		7.5	10.5	1	11.5	1	11.5	118
tsk(o)			C _L = 50 pF			1**				1	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

^{**} On products compliant to MIL-PRF-38535, this parameter does not apply.



^{**} On products compliant to MIL-PRF-38535, this parameter does not apply.

SN54AHC16373, SN74AHC16373 **16-BIT TRANSPARENT D-TYPE LATCHES** WITH 3-STATE OUTPUTS SCLS329G - MARCH 1996 - REVISED JANUARY 2000

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	SN74	AHC16	373	UNIT
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.34	0.8	V
VOL(V)	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		4.6		V
VIH(D)	High-level dynamic input voltage	3.5			V
V _{IL} (D)	Low-level dynamic input voltage			1.5	V

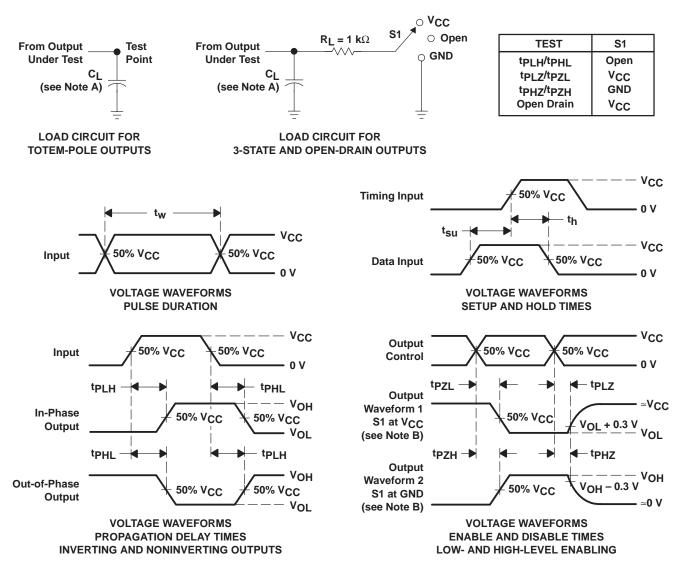
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C _{pd} Power	dissipation capacitance	No load,	f = 1 MHz	21	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms









10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC16373DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC16373	Samples
SN74AHC16373DGVR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HE373	Samples
SN74AHC16373DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC16373	Samples
SN74AHC16373DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC16373	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and



PACKAGE OPTION ADDENDUM

10-Dec-2020

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC16373DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AHC16373DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AHC16373DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

www.ti.com 3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC16373DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74AHC16373DGVR	TVSOP	DGV	48	2000	356.0	356.0	35.0
SN74AHC16373DLR	SSOP	DL	48	1000	367.0	367.0	55.0

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AHC16373DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated